ABSTRACT

SUPPLY MECHANISM FOR THE CHUCK OF AN INTEGRATED CIRCUIT DICING DEVICE

A system for dicing substrates to singulate integrated circuit units includes a dicing machine (Z) which operates with a chuck table (4). A lifting assembly (Ax, Ay) deposits substrates to be singulated onto the chuck table (4) at substantially the same time as it removes previously singulated units from the chuck table (4). Also disclosed is a support device fixing the diced chips by vacuum to an insert of a soft material.

Figure 1(a)

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